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MV Semi-conductor

Application _____

Field
Laboratory**PRODUCT BENEFITS**

Remove the use of knife for a increased security

TOOL CAPACITY

Diameter	10 - 80 mm 0,394 - 3,150 inch
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Type of semiconductor	Smooth peelable or ribbed
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TOOL DIMENSIONS

Length	110 mm
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Width	35 mm
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Height	35 mm
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Weight without box	0,13 Kg
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Packaging	None
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Tool to remove the peelable semiconductor**TO DO WHAT**

The Dsp tool allows to remove and catch the peelable semiconductor at the end of cable to remove it by hand

**Associated tool**

MF1+/25 - Multifunction tool for bonded semiconductor

SR - Scoring stylus for peelable semiconductor

SRC - Scoring stylus for peelable semiconductor with chamfer

MF1+/60 - Multifunction tool for bonded semiconductor

SRC-D - Scoring stylus for peelable semiconductor with chamfer on the transition

MF3/40 - Multifunction tool for outer sheath, peelable semiconductor and insulation

MF3/60 - Multifunction tool for outer sheath, peelable semiconductor and insulation

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Part Number	Diameter	Tool capacity	Dimensions			Packaging
		Type of semiconductor	Length	Width	Height	
DSP	10 - 80 mm 0,394 - 3,150 in	Smooth peelable or ribbed	110 mm 4,331 in	35 mm 1,378 in	35 mm 1,378 in	none